

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3308	substrate and (flexible near3 adhesive)	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/12/14 10:35
L2	1418	(flexible near3 substrate) and (flexible near3 adhesive)	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/12/14 10:35
L3	39	(flexible near3 substrate) and (flexible near3 adhesive) and (modulus near3 elasticity)	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/12/14 10:36
L4	21	(flexible near3 substrate) and (flexible near3 adhesive) and (modulus near3 elasticity) and foil	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/12/14 10:36
L5	19	(flexible near3 substrate) and (flexible near3 adhesive) and (modulus near3 elasticity) and foil and (component or device or IC or chip)	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/12/14 10:45
L6	43620	substrate and adhesive and pattern	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/12/14 10:45
L7	31	(adhesive near4 (elasticity near4 modulus) near4 temperature)	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/12/14 10:48
L8	22	(adhesive near4 (elasticity near4 modulus) near4 temperature) and (substrate or board)	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/12/14 10:58
L9	21	(adhesive with (elasticity with modulus) with (glass with temperature)) and (substrate or board)	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/12/14 11:02
L10	52	adhesive and (glass adj temperature) and flex\$3	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/12/14 11:03
L11	29	adhesive and (glass adj temperature) and (modulus near4 elasticity)	USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/12/14 11:08